



## Material Content Data Sheet



<b>Sales Product Name</b>		BSP372N H6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA001100396						
<b>Package</b>		PG-SOT223-4-21		<b>Weight*</b>		113.62 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.041	0.04		363	
	non noble metal	tin	7440-31-5	0.011	0.01		94	
	inorganic material	silicon	7440-21-3	0.630	0.55	0.60	5542	5999
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		446	
	non noble metal	chromium	7440-47-3	0.152	0.13		1339	
	non noble metal	copper	7440-50-8	50.489	44.44	44.62	444369	446243
wire	non noble metal	copper	7440-50-8	0.103	0.09	0.09	910	910
encapsulation	organic material	carbon black	1333-86-4	0.602	0.53		5294	
	plastics	epoxy resin	-	9.023	7.94		79417	
	inorganic material	silicondioxide	60676-86-0	50.531	44.48	52.95	444737	529448
leadfinish	non noble metal	tin	7440-31-5	1.464	1.29	1.29	12885	12885
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4515	4515
*deviation	< 10%		Sum in total:			100,00		1000000

### Important Remarks:

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